

EE 330 Coverage - Fall 2007

Topics

Week	1	1 Electronic Systems Overview, Economic Opportunities 2 Yield and Cost of Semiconductor Products 3 Physical characteristics, soft faults
Week	2	4 Digital Systems - Basic Gates, Switch-Level MOS Models 5 Digital Systems - Complex Logic Gates, Pass Transistor Logic, Improved Switch-Level MOS Model 6 Parameter Extraction for Imp. Switch-Level Model, Propagation Delay in Logic, Placement, Stick Diagrams
Week	3	Holiday 7 Technology Files, Design Rules, Layout 8 Fabrication Technology, Processing Steps
Week	4	9 Fabrication Technology, Processing Steps 10 Interconnects - resistive and capacitive 11 Backed Technology - Packaging, Bonding, Basic Semiconductor Processes
Week	5	12 Devices/Device Models in Semiconductor Processes - Resistors, Diodes 13 Diode Operation, Diode Model (Diode Equation), simplified diode models 14 Diode Applications, Capacitor types and Models, MOSFET operation
Week	6	15 MOSFET Operation - square law model, short channel model, BSIM model (brief) 16 MOS Process Description - (n-channel, p-channel, capacitors, resistors) 17 Exam 1
Week	7	18 Small feature MOS processes, Bipolar Devices and operation 19 Bipolar Devices - operation, device model, simplified device model 20 Bipolar Process Description - (vertical and lateral devices, JFET, diffused resistor, varactor, diode)
Week	8	21 MOS and Bipolar Device Comparisons, Q-point calculation 22 Transistors as Amplifiers (MOS and Bipolar) 23 Small-signal principles, ss models of 2-terminal devices, ss diode model
Week	9	24 Small-signal models of 3-terminal and 4-terminal devices, small signal MOSFET model 25 Small-signal BJT models, small signal circuit analysis, load lines, signal swings 26 MOSFET Model Extension (Bulk threshold), Comparison of MOS and Bipolar devices as amplifiers, Dependence of SS parameters on Q-point
Week	10	27 Basic Amplifier Structures-CS/CE, CD/CC, CG/CB 28 Basic Amplifier Structures-CS/CE, CD/CC, CG/CB 29 High Gain Amplifiers- Cascoding
Week	11	30 High Gain Amplifiers - Cascoding, Cascading 31 Current Source Biasing, Darlington Configuration 32 Current Sources and Mirrors
Week	12	33 Differential Amplifiers (brief), Bipolar and MOS Mappings 34 Hierarchical Digital Design - Behavioral, Structural, Physical, Digital Design Flows 35 Basic Gates, Characteristics of Logic Families, the Inverter Pair
Week	13	36 Analysis of Logic Circuits (at transistor level), VH, VL, VTRIP, Static I/V Char of CMOS Inverter, Inverter Device Sizing 37 Other CMOS Logic (ratio logic), Propagation Delay in Static CMOS, Logic Gate Device Sizing, Reference Inverters 38 Propagation Delay in Multiple Levels of Logic, Overdrive
Week	14	39 Asymmetric Overdrive and Propagation Delay, Driving large capacitive loads 40 Pad Drivers, Logical Effort, Elmore Delay, Ring Oscillators 41 Exam 2
Week	15	42 Complex Logic Gates, Pass Transistor Logic, Pseudo NMOS, Dynamic Logic (Domino and Zipper) 43 Sequential Logic - Latches, Flip Flops, Shift Registers, Array Logic, Sea of Gates and Gate Arrays 44 Memory Structures - Row/Column Decoders, Mem Cells (SRAM, DRAM, SROM, EEPROM) High Frequency MOS Model (not enough time to cover)